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SEMICONDUCTOR THIN (54) MANUFACTURE OF

(57) Abstract:

consisting of fluorosilane, silane or, single crystalline substrate by photoa single crystalline or amorphous desirably, hydrogen. discomposing a mixture gas thin film with superior orientation on PURPOSE: To form a semiconductor

crystallineor amorphous single CONSTITUTION: A single

which has at least a light permiating placed in a thin film forming device 7 cleaned with washing or etching is crystalline substrate whose surface is group compounds, phosphine (PH3) discharge means 6, and the substrate 3, a substrate heating means 4, a gas window 1, a substrate holding means or arsine (AsH3) is usable. dibolane (B2H6) is usable. As V to be added to the mixture gas, usable. As the III group compounds SimH2m+2 (integer of m=1W3) are disilane, trisilane expressed with usable. As the silane, monosilane, nFn(integer of n=1W3) or Si2F6 is the flowing ratio of silane to is supplied to the said device, with vaccum discharge. The material gas is heated to 100W400°C under introduction means 5 and a vaccum former. As the fluorosilane, SiH4fluorosilane being more than twice he flowing ratio of hydrogen to the fluorosilane being 0.5W50 and the

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